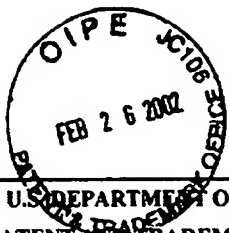


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Form PTO-1449 (REV. 07/01)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. INDUM-108XX		APPLICATION NO. 10/008,853	
INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)				APPLICANT: Wusheng Yin, et al.			
				FILING DATE 11/15/01		GROUP 2811	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE*
PAZ		5,128,746	7/7/92	Pennisi et al	357	72	
PAZ		6,038,136	3/14/00	Weber	361	783	
PAZ		6,157,086	12/5/00	Weber	257	788	
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
PAZ		WO 99/56312	11/4/99				
OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)							
PAZ	A Novel Approach to Incorporate Silica Filler into No-Flow Underfill, Zhuqing Zhang, et al., School of Materials Science and Engineering and Packaging Research Center, Georgia Institute of Technology, Atlanta, GA, pp. 1-7.						
PAZ	No Flow Underfill Materials for Environment Sensitive Flip-Chip Process, A Dissertation Presented to The Academic Faculty, Zhuqing Zhang, Georgia Institute of Technology, June 2001, pp. 1-125.						
PAZ	"No-Flow" Underfill Reliability is Here - Finally!, Michael A. Previti, Cookson Semiconductor Packaging Materials, Alpharetta, GA, Session P-MT1, pp. 1-4.						
PAZ	The Development of No-Flow Underfill Materials for Flip-Chip Applications, Advisor Dr. C.P. Wong, Student S.H. Shi, School of Materials Science and Engineering and Packaging Research Center, Georgia Institute of Technology, Atlanta, GA, February 2, 1999.						
EXAMINER 				DATE CONSIDERED 7/15/03			
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							



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(REV. 07/01)

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO.
INDUM-108XX

APPLICATION NO.
10/008,853

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

APPLICANT:

Wusheng Yin, et al.

FILING DATE
11/16/01

GROUP
2811

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE*

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO

OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)

	<u>Surface Mount Technology, Materials, Processes and Equipment</u> , Carment Capillo, UNISYS Corporation, Network Computing Group, San Jose, CA, McGraw-Hill Publishing Co.
	<u>Epoxy Flip Chip Flux PK-001</u> , Indium Corporation of America, Form No. 97727 R0.
	<u>Pb-Free Epoxy Flip Chip Flux PK-002</u> , Indium Corporation of America, Form No. 97728 R0.

EXAMINER

DATE CONSIDERED

7/15/3

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